

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	4	ubm and scraper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 08:40
L3	283	lin.inv. and electroless	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 09:00
L4	134	lin.inv. and electroless and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 09:01
L5	22	lin.inv. and electroless and "438"/\$.ccls. and ubm	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 09:02
L6	14	lin.inv. and electroless same ubm and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 09:02
S2	23	bumping same (led electrode\$1) and (under adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/21 16:43
S3	13	bumping same (led electrode\$1) and (under adj bump) and reflow\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/21 16:43
S4	473	bumping same (led electrode\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 17:13
S5	15	S4 and print\$4 and metallurgy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:57
S6	58	S4 and reflow\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:54

S7	47	S4 and reflow\$4 not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:55
S8	90	S4 and plating\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:56
S9	73	S4 and plating\$1 and solder\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:56
S10	0	S4 and (openning\$1 cavit\$3 hole\$1 recess\$3) same wage\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 15:58
S11	21	S4 and (openning\$1 cavit\$3 hole\$1 recess\$3) same wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:01
S12	44	(led adj chips) same (posts electrodes) same bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:02
S13	264	(led adj chips) same (posts electrodes) not S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:05
S14	1467	(led near5 chips).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:06
S15	30	S14 and bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:06
S16	2	S14 and (under adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:12
S17	23	S4 and (under adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:09

S18	596	(under adj bump) same deposit\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:14
S19	10	(under adj bump) same deposit\$4 and umb same (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:17
S20	9	(under adj bump) same deposit\$4 and umb same etch\$4 and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:19
S21	9	(under near bump) same deposit\$4 and umb same etch\$4 and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:19
S22	9	(under near bump) same deposit\$4 and UMB same etch\$4 and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:20
S23	188	(under near bump) same deposit\$4 and UBM same etch\$4 and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:20
S24	206	(under near bump) same deposit\$4 and UBM same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:21
S25	92	(under near bump) same deposit\$4 and UBM same (contact) same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:22
S26	89	(under near bump) same deposit\$4 and UBM same (contact) same layer\$1 same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:22
S27	65	(under near bump) same deposit\$4 and UBM same (contact) same layer\$1 same passivat\$4 same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:48
S28	35	S27 and plated same photoresist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:31

S29	3	S27 and plated same photoresist and led\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:32
S30	4	S27 and plated same photoresist and (led\$2 diode\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:33
S31	14	(under near bump) same deposit\$4 and UBM same (contact) same layer\$1 same passivat\$4 same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb) and (led\$2 diode\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 18:08
S32	0	(under near bump) same deposit\$4 and UBM same (contact) same layer\$1 same passivat\$4 same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb) and (led\$2 diode\$1) same (contacts pads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:49
S33	14	(under near bump) same deposit\$4 and UBM same (contact) same layer\$1 same passivat\$4 same (photoresist\$1 etch\$4) and (copper alumminum Sn Pb) and ((light adj emit\$5) led\$2 diode\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 08:39
S34	198	UBM same (led electrode\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 09:00
S35	13	UBM same (led)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 17:16